



MICROWAVE PRODUCTS DIVISION

LSP1000 thru LSP1012

ENHANCED PERFORMANCE
SURFACE MOUNT "EPSM" PACKAGED DEVICES

PRODUCT PREVIEW

DESCRIPTION

Our EPSM packaged devices are designed for the most demanding commercial and Military requirements where the inconsistency of performance inherent in plastic surface mount packages cannot be tolerated. These package styles extend the surface mount construction format to 6 GHz for high performance wireless applications including VCO's, limiters, pin switches and pin attenuators. Select PIN diodes for switching, attenuation or limiting through 6 GHz. They are available in multiple chip configuration as well as outlines which directly replace SOT-23 and SOD-323 devices. Other devices and values are always available - contact our applications engineering department for more details.

IMPORTANT: For the most current data, consult *MICROSEMI*'s website: <http://www.microsemi.com>

**PIN DIODE DEVICES FOR WIRELESS ATTENUATORS,
SWITCHES AND LIMITERS****ABSOLUTE MAXIMUM RATINGS AT 25°C**

Forward Current (I_F): 1 Amp (1μs Pulse)

Power Dissipation (P_D): 500 mW
(Derate to 0 at max T_J)

Peak Inverse Volts (PIV): Same as V_B

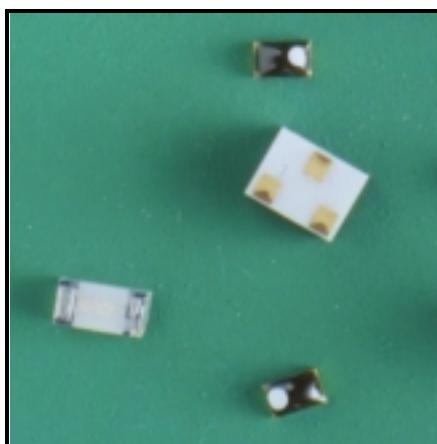
Junction Temp. (Operating): -65°C to + 125°C

Storage Temp. (Non-Operating): -65°C to + 125°C

Leakage: <50 nA @ 80%
V_B @ 25°C

TEST CONDITIONS:

V_B @ 10 μA R_S @ 100 MHz
C_T @ 1 MHz T_L @ I_F = 10 mA
I_R = 6 mA



KEY FEATURES

- Frequencies from VHF to 6 GHz
- Lower Parasitics
- Mil Grade Ceramic/Epoxy Amalgam Construction
- Dense SiO₂ Junction Passivation
- Superior Consistency/Repeatability
- Footprints Available for SOT-23/SOD-323/SOD-123
- Priced for Commercial Products
- Tape & Reel for Volume Pick & Place

APPLICATIONS/BENEFITS

- High performance wireless surface mounting including:
- GSM
- TAGS
- WANS
- PCS
- AMPS
- DECT
- CELLULAR

TABLE 1

| MODEL | V _B | C _T @ V _R MAX. | R _S @ IF MAX. | T _L TYP. | APPLIC-TION |
|---------|----------------|--------------------------------------|--------------------------|---------------------|-------------|
| LSP1000 | > 35 | .28 @ 5V | 2.5Ω @ 5 mA | 80nS | SWITCH |
| LSP1002 | > 100 | .32 @ 50V | 4Ω @ 100 mA | 1500nS | ATTENUATOR |
| LSP1004 | > 35 | .75 @ 20V | 0.6Ω @ 10 mA | 150nS | SWITCH |
| LSP1011 | > 200V | .35 @ 50V | 2Ω @ 100 mA | 2000nS | ATTENUATOR |
| LSP1012 | > 20V | .35pF @ 10V | 1.8Ω @ 10 mA | 5nS | LIMITER |



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EPSM AVAILABLE CONFIGURATIONS

Figure 1 Outline Style 150(X)

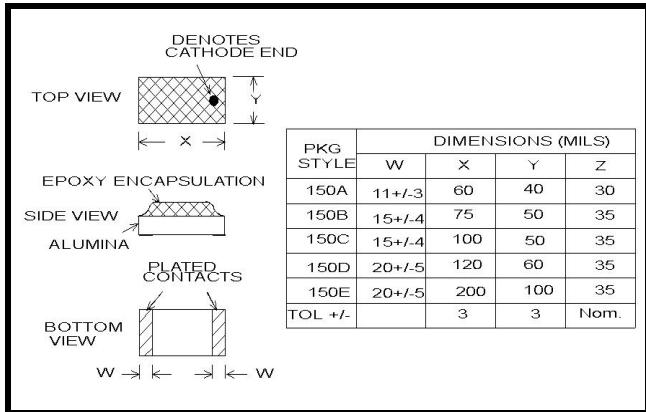


Figure 2 Outline Style 154

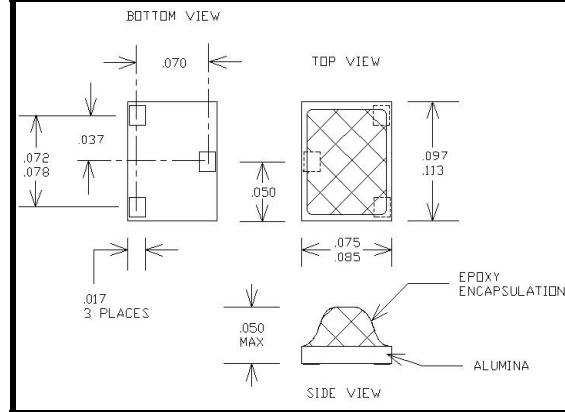


Figure 3 Outline Style 250(X)

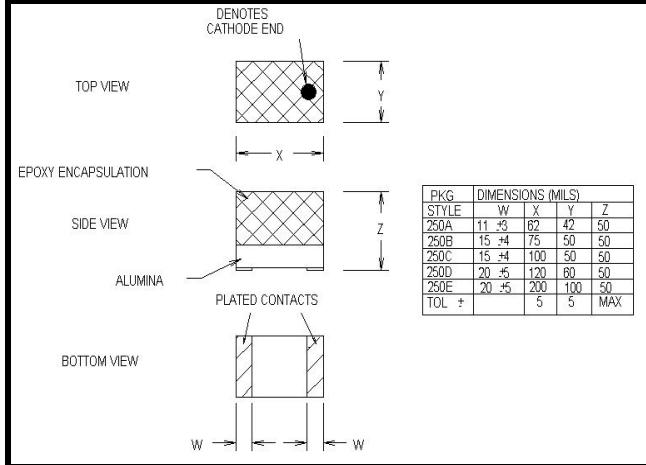


Figure 4 Outline Style 254

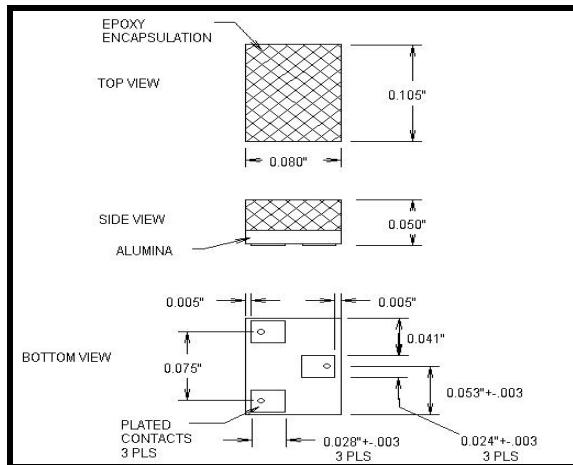


Figure 5 Outline Style 350(X)

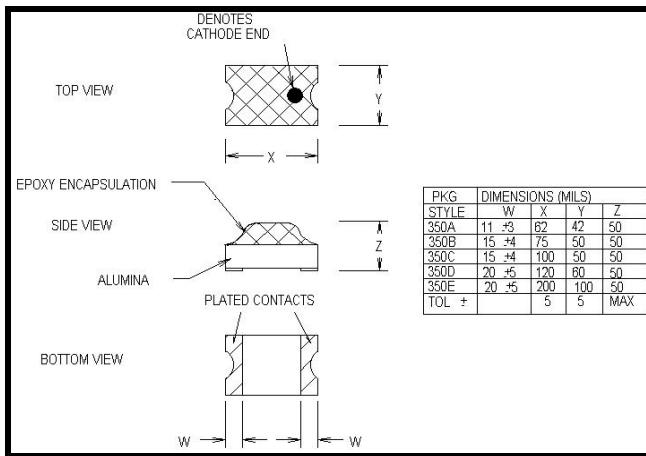
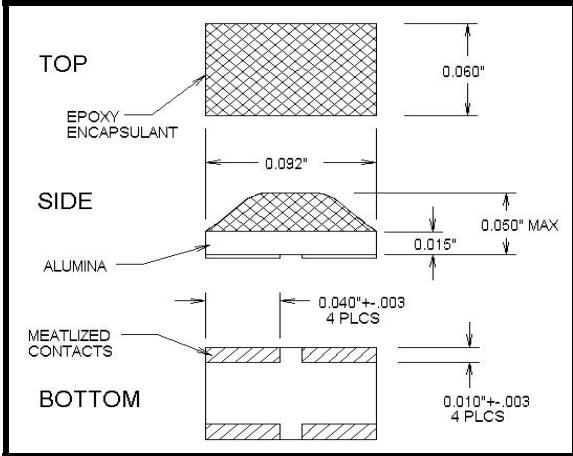


Figure 6 Outline Style 252A





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NOTES